

Abstracts

Grounding Microstrip Lines with via Holes (Short Papers)

D.G. Swanson, Jr.. "Grounding Microstrip Lines with via Holes (Short Papers)." 1992 Transactions on Microwave Theory and Techniques 40.8 (Aug. 1992 [T-MTT]): 1719-1721.

Grounding microstrip circuits with via holes is an established technology and modeling isolated via holes with analytical models is well known. However, the availability of electromagnetic field solvers provides an opportunity to model via holes and the metalization surrounding them in a more realistic fashion. Calculated equivalent inductances for single and double via hole configurations are presented. A microstrip interdigital filter with grounded resonators provides experimental verification.

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